



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten up The World With LED!



ISO 9001:2009



ISO 14001:2004



IEC 90000 IECQ HSP9000

PRODUCT DATASHEET



- ▶ PCB / CHIP LED
- ▶ 0805 0.8t Series
- ▶ Red (630nm) / Green (525nm) / Blue (470nm)

NOM25S67



Release Date: 23 February 2016 Version: A1.0



0805 0.8t Series

0805 0.8t Series



FEATURES:

- **Package:** PCB SMT Package Top View Multi Colours
- **Forward Current:** 20/20/20mA*
- **Forward Voltage (typ.):** 1.9/3.2/3.2V
- **Luminous Intensity (typ.):** 100/500/125mcd @20mA
- **Colour:** Red/Green/Blue
- **Wavelength:** 630/525/470nm
- **Viewing angle:** 140/140/140°
- **Materials:**
 - Die: AlGaInP/InGaN/InGaN
 - Resin: Epoxy (Water Clear)
- **Operating Temperature:** -20~+80°C
- **Storage Temperature:** -30~+100°C
- **ESD:** 2000/500/500V
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - Dominant Wavelength
- **Soldering methods:** Reflow
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 8mm tape with 4000/reel, ø180mm (7")

* in the order of Red/Green/Blue

APPLICATIONS:

- Indication Light
- Switch light
- Dashboard
- Keyboard
- Consumer Goods

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I_F	50/30/30*	mA
Peak Forward Current Duty 1/10@10KHz	I_{FP}	130/100/100	mA
Reverse Current @5V	I_R	10/50/50	μ A
Power Dissipation	PD	120/108/108	mW
Electrostatic Discharge	ESD	2000/500/500	V
Operating Temperature	T_{OPR}	-20~+80	°C
Storage Temperature	T_{STG}	-30~+100	°C

* in the order of Red/Green/Blue

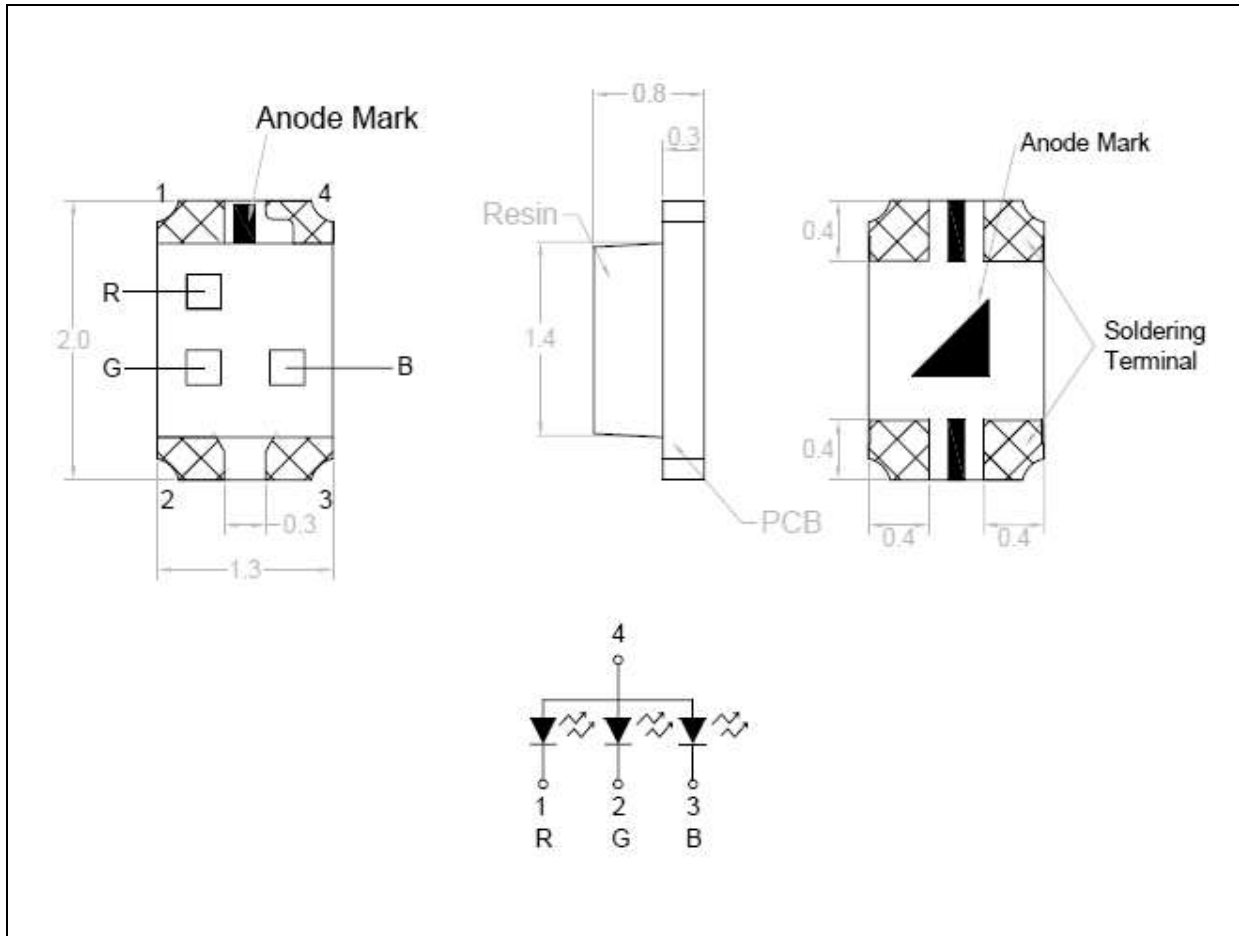
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V_F	1.5/2.8/2.8	---	2.4/3.6/3.6	V	$I_F=20mA$
Luminous Intensity	I_V	32/200/50	100/500/125	125/1250/200	mcd	$I_F=20mA$
Dominant Wavelength	λ_D	---	630/525/470	---	nm	$I_F=20mA$
Spectral Line Half Bandwidth	$\Delta \lambda$	---	20/36/30	---	nm	$I_F=20mA$
Viewing Angle	$2\theta_{1/2}$	---	140/140/140	---	deg	$I_F=20mA$

1. Luminous intensity (I_V) $\pm 15\%$, Forward Voltage (V_F) $\pm 0.1V$

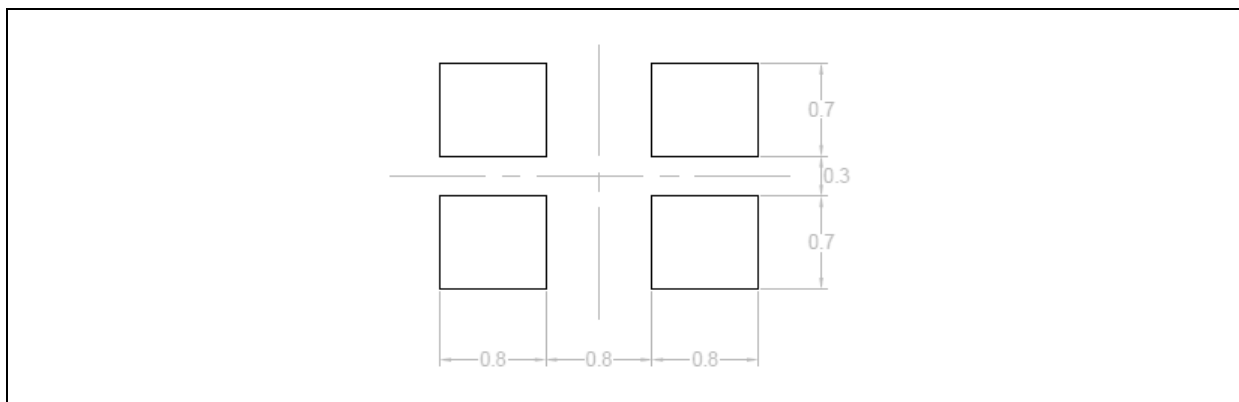
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.2\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 20\text{mA}$):

Code	Min.	Max.	Unit
Red	1.5	2.4	V
Green	2.8	3.6	
Blue	2.8	3.6	

 Luminous Intensity Classifications ($I_F = 20\text{mA}$):

Code	Min.	Max.	Unit
Red	N	32	mcd
	P	50	
	Q	80	

Green	S	200	mcd
	T	320	
	U	500	
	V-1	800	
	V-2	1000	

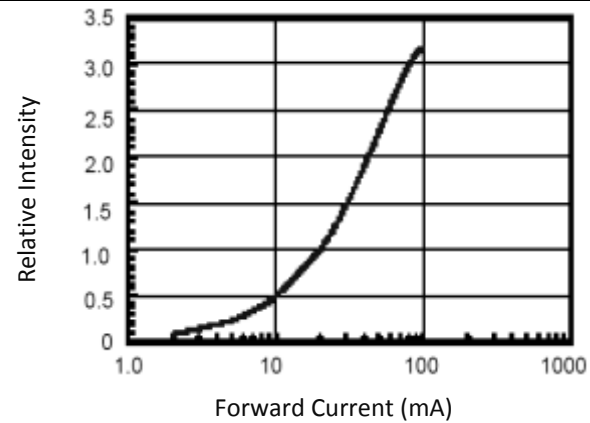
Blue	P	50	mcd
	Q	80	
	R	125	

 Dominant Wavelength Classifications ($I_F = 20\text{mA}$):

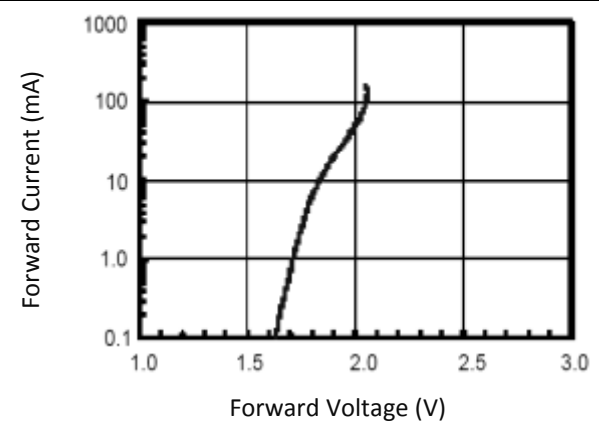
Code	Min.	Max.	Unit
Red	620	640	nm
Green	520	530	
Blue	465	475	

ELECTRO-OPTICAL CHARACTERISTICS (RED):

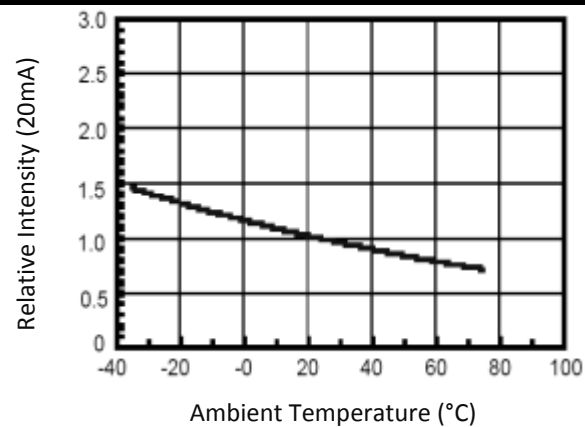
Relative Intensity v.s. Forward Current



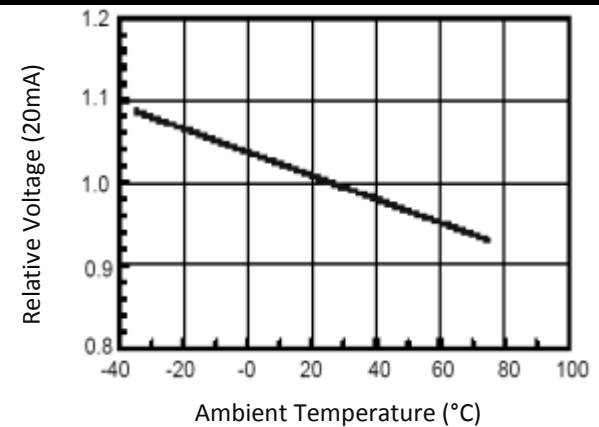
Forward Current v.s. Forward Voltage



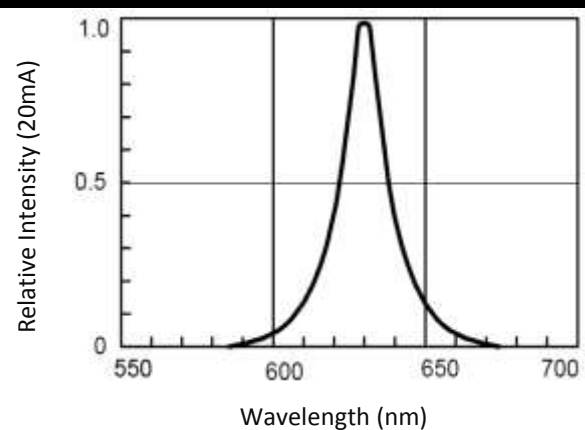
Relative Intensity v.s. Temperature



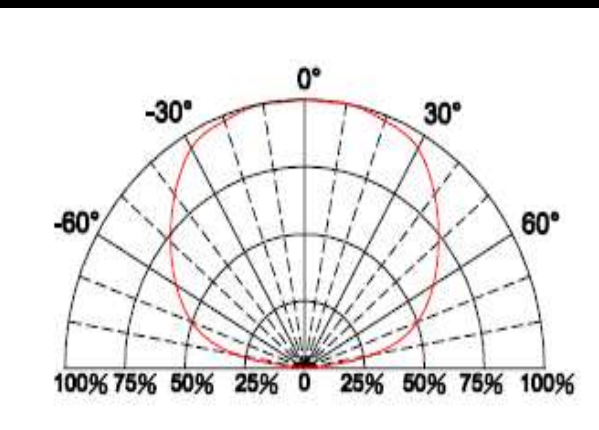
Relative Forward Voltage v.s. Temperature

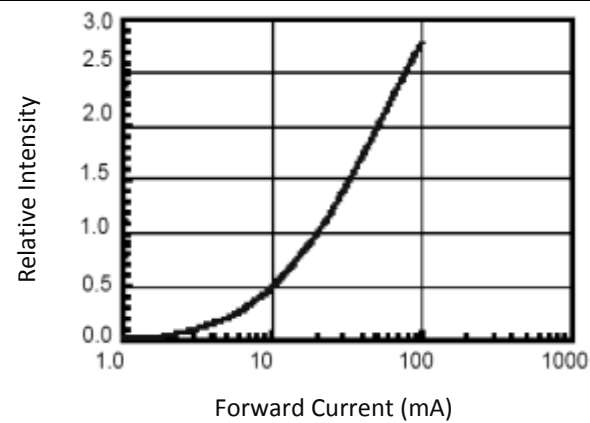
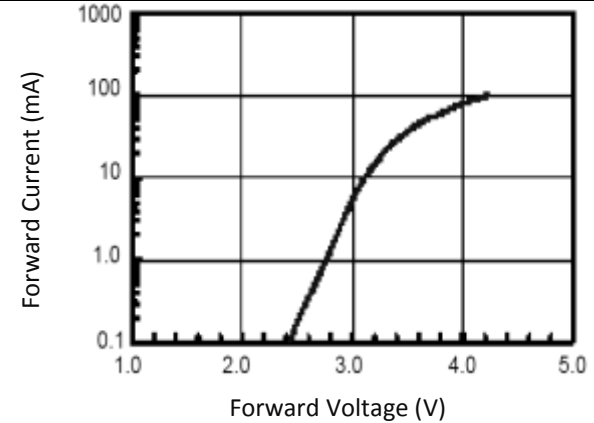
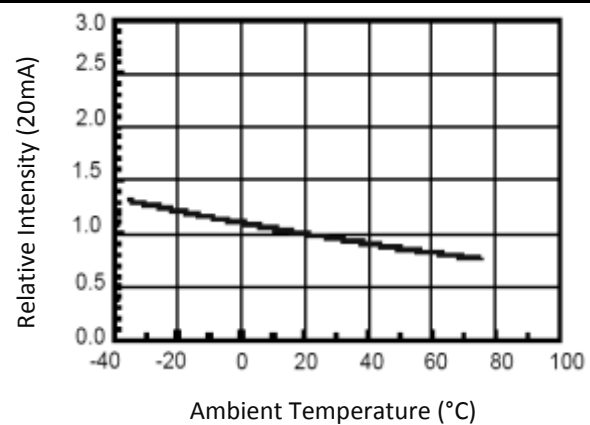
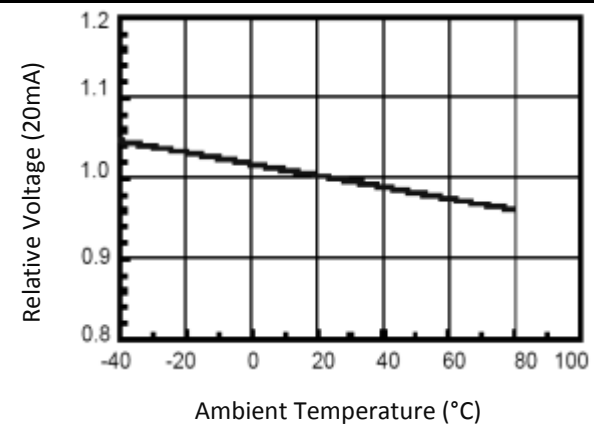
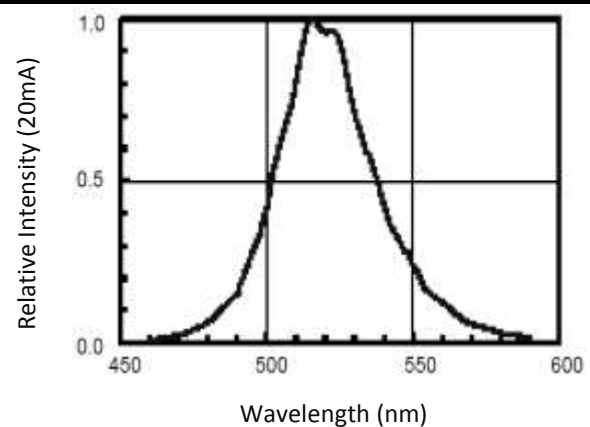
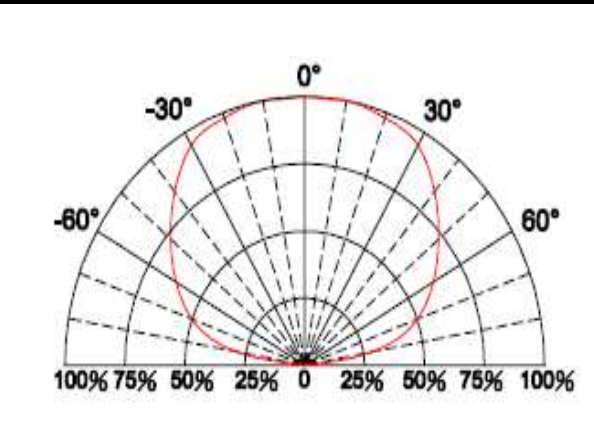


Relative Intensity v.s. Wavelength



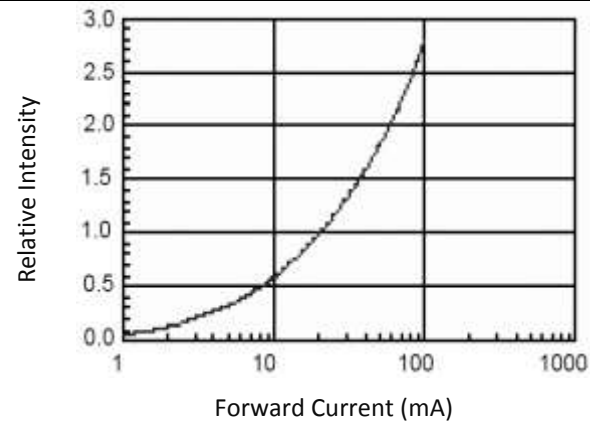
Directive Radiation



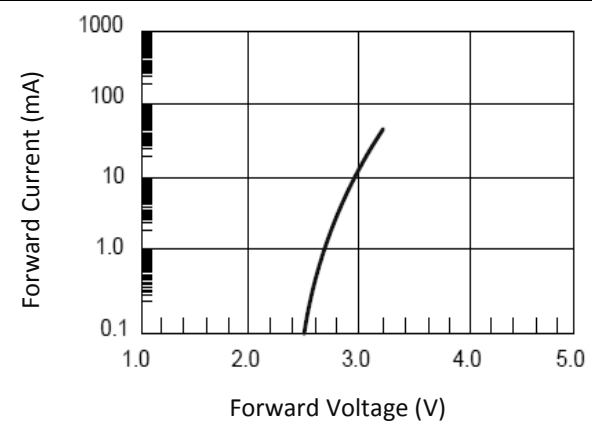
ELECTRO-OPTICAL CHARACTERISTICS (GREEN):
Relative Intensity v.s. Forward Current

Forward Current v.s. Forward Voltage

Relative Intensity v.s. Temperature

Relative Forward Voltage v.s. Temperature

Relative Intensity v.s. Wavelength

Directive Radiation


ELECTRO-OPTICAL CHARACTERISTICS (BLUE):

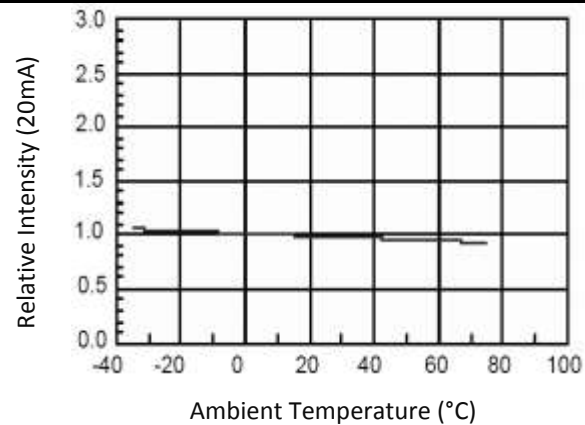
Relative Intensity v.s. Forward Current



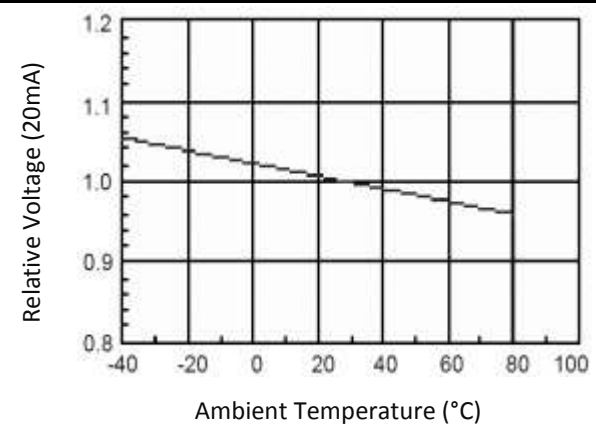
Forward Current v.s. Forward Voltage



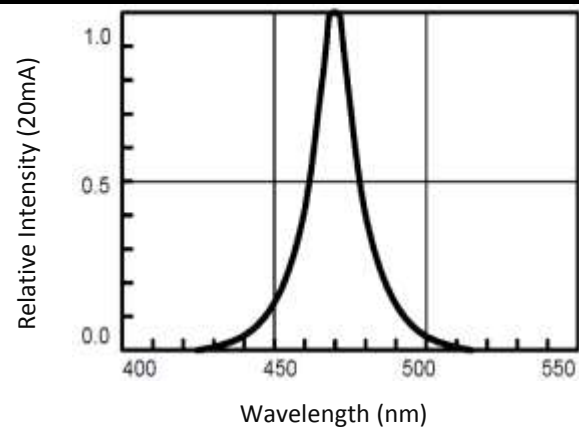
Relative Intensity v.s. Temperature



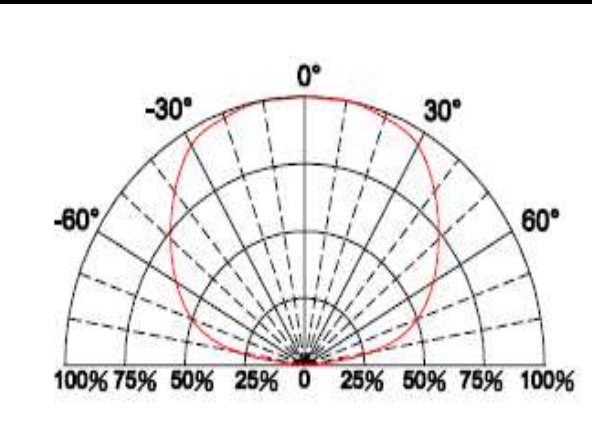
Relative Forward Voltage v.s. Temperature



Relative Intensity v.s. Wavelength

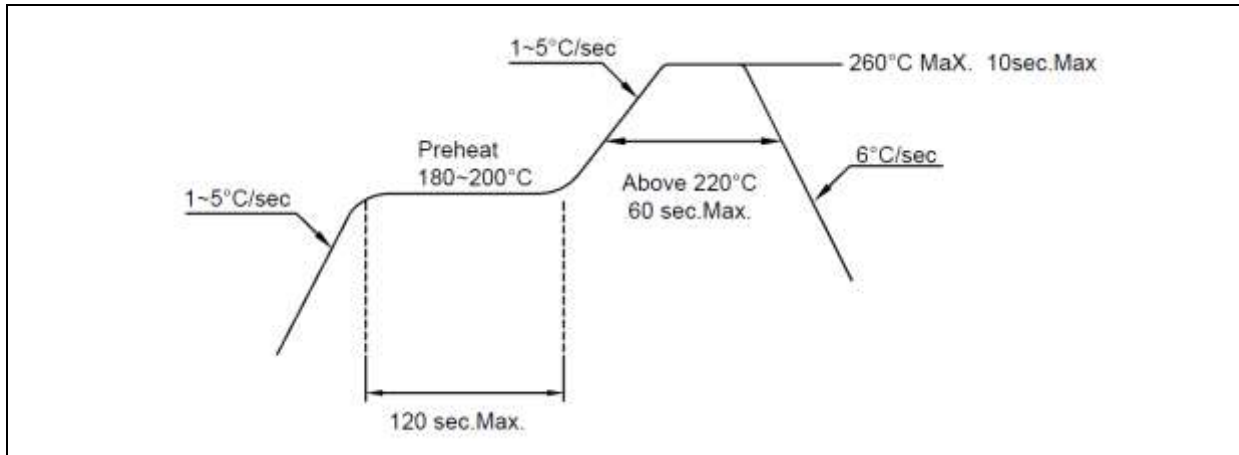


Directive Radiation



RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:

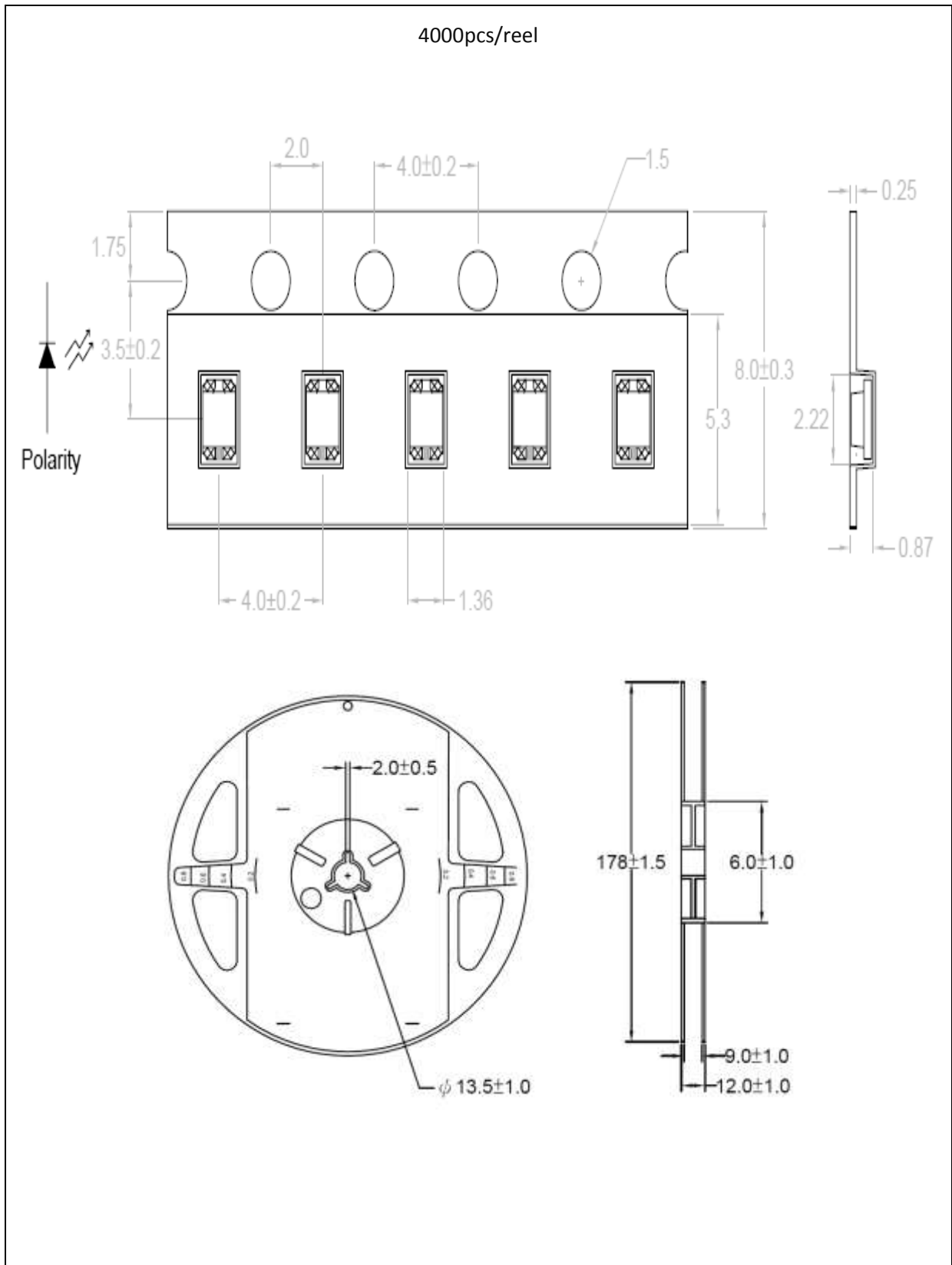


Note:

1. Maximum reflow soldering: 2 times.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent and apply baking at 60°C±5°C for 15hrs before use.

Baking:

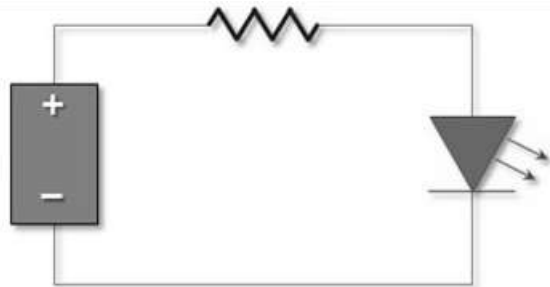
It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs.

The suggested baking conditions are as follows:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	23/02/2016	Datasheet set-up.